

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1763IDE-1.8#TRPBF		(Engineering Calculation)		DFN 4mm X 3mm Exp. Pad				
(printed on: 7/26/2011 6:02:48 AM)				TOTAL MASS (g):		0.03167184		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001864	1000000	58853.55		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.012783	975000	403607.8		
		Iron (Fe)	7439-89-6	0.000315	24000	9945.745		
		Phosphorus (P)	7723-14-0	4.00E-06	300	126.2952		
		Zinc (Zn)	7440-66-6	9.00E-06	700	284.1642		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.013111	1000000	413964
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.000606835	1000000	19160.07		
		External Plating Total:				0.000606835	1000000	19160.07
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	0.000295	1000000	9314.269		
		Internal Plating Total:				0.000295	1000000	9314.269
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000876	750000	27658.64		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0.000292	250000	9219.548		
Die Attach Total:				0.001168	1000000	36878.19		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001888	130000	59611.32		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.012487	860000	394261.9		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	0.000145	10000	4578.2		
Encapsulation Total:				0.01452	1000000	458451.4		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000107	1000000	3378.396		
Estimated								
				TOTAL MASS (g):		0.03167184		